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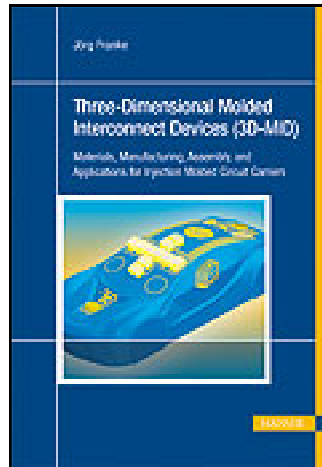

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Three-Dimensional Molded Interconnect Devices (3D-MID)

Materials, Manufacturing, Assembly and Applications for Injection Molded Circuit Carriers

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Index

Symbol
3D 2
3D capability 117
3D development environment, integrated 258
3D switching module 290
3D wiring 11
6-axis multiple-articulation robot 130, 131

A
ablation, photo-chemical 55
ACA 145
accessibility 117
ACC position sensor 282
acrylonitrile butadiene styrene 42
ADDIMID technology 70
additives 40
adhesives, nonconductive 147
adhesive strength 56, 182
adhesive tape 186
advanced interconnect technology process 88
Aerosol-Jet® printing 214
air-conditioning 279
aluminum oxides 50
anisotropic conductive-adhesive gluing 158
anisotropic conductive adhesives 145, 147
antennas 11
AOI 178
application of connection medium 118
aspect ratio 71
assembly 273
– automated 118
automated optical inspection 178
automated workpiece carrier 132, 133, 134
automotive 9, 282, 283, 290, 294, 296

B
ball grid array (BGA) components 121
ball-pressure hardness 31
bare die 125
beaker 100
beta rays 48
bonding 106
boron nitrides 50
bubble-jet print head 78

C
CAD 255
CAD/CAM chains 271
calculation of warpage 269
CAM 271
capillary flow underfill 163
capture decal process 88
Cartesian gantry system 128, 130
casting 171
cavity filling 266
ceramic 25, 28, 71
characteristic values
– electrical 37
– mechanical 29
characterization, electrical 189
chemical structure 24
chip placement 162
chisel test 184
classification, geometric 2
cleaning 96
– wet-chemical 96
CO_2 snow-jet cleaning 97
coefficient of expansion
– thermal 140, 193
coefficient of thermal expansion (CTE) 36, 139, 193
coefficient of thermal transfer 150
coining 167

cold plasma 92
composites 23
compressed-air dispenser 120
computer-aided design 255
computer assistance 254
computerized tomography 180
concept model 202
concurrent or simultaneous engineering 254
condensation 149, 152
conduction 149
conductive-adhesive gluing 113, 157
conductive adhesives
– anisotropic 147
– isotropic 145
connection medium, application 118
connection mediums 143
CONSENS 226
controlled collapse chip connection new process (C4NP) 167
convection 149
convection soldering oven 155
cooling system 268
copper 50
copper bath 99
creep resistance, electrical 38
cross-cut test 185
crosslinking, radiation-induced 46
CTE 36, 140, 193
Curing process 77
current-carrying capability 106, 191
CVD 93
cycle time 269, 272

D

damping, mechanical 33
degree of fill 51
degree of freedom 115
design 261
– DFM 232
– mechanical 254
design catalogs 246
design for manufacturing (DFM) 232
design rule checks 259
design rules 256
development environment, three-dimensional 256
development, integrative 217
development methodology 218
development tool, MID-specific 263
device library 263, 264
die bonding 165
die-emboss smoothing 104
dielectric constant 38
dipping components 121
direct metal laser sintering 210
dispensing 119
DMA 33
DRC 259, 265
dynamic mechanical analysis 33

E

ECAD 255, 261
ECAD-MCAD collaboration 262
ECAD-MCAD development 257
EDA 256
electrical characteristic values 37
electrical characterization 189
electrical creep resistance 38
electrical MID functions 247
electrical puncture resistance 38
electro-mechanical 264
electron beams 47
electronic computer-aided design 255
electronic design automation 256
electronic layout design 254
electronics design 235
embossing die 84
engineering thermoplastics 39
environmental compatibility 5, 76
environmental influences, protection against 170
etch resist 72

F

FDM process 207, 212
features 252
fibers 51
fiducials 117
filler 40, 50, 193
film insert molding 5, 85
film technology 8
Flamecon® 91, 271
flexural test 31
flip chip 162
flip-chip components 121
flip-chip technology 166
flow sensor 279
friction, internal 33
fully functional samples 203

function, optical 12
fused deposition modeling 207

G
galvano-chemical metallization 97
galvanoresist 72
gamma rays 48
gantry system, Cartesian 128, 130
geometric classification 2
glass transition temperature 34
glob top 168
gluing, with anisotropic conductive adhesive 158
graphites 50
guidelines 250

H
hardness 31
hearing aid 295
heat deflection temperature (HDT) 34
heat distortion temperature 34
high-performance plastics 39
hot embossing 5, 80, 214
hot-embossing films 82
hot-embossing process 81
humidity heat test 195

I
ICA 145
impact bending test
– Charpy 32
– Izod 32
industrial automation 10, 288, 298
industrial robots 131, 271
injection compression molding 86
injection molding 209
injection-molding process 52
injection-molding tool 209, 268
inkjet printing 77
inks 76
in-mold decoration 85, 86
in-mold labeling 86
insert molding 85
in situ locating 117
inspection, optical 135
instruments of development 246
insulating properties 192
insulation behavior 37
insulin pump 286
integral design 217
integrated 3D development environment 258
integrative development 217
interconnect device 11
interfaces 260
interfacing to periphery 169
intermetallic phase 149
internal friction 33
isotropic conductive adhesives 145
IT communication 10

J
jet printing 120
joining direction 115

K
kinematic variants 123

L
laser activation 55
laser beam melting 210
laser beam soldering 156
laser cladding 206, 210
laser debris 98
laser direct structuring 53, 57, 249
laser microscopy 177
laser sintering 206, 210
– selective 206
laser structuring 5, 64
laser subtractive structuring 72
layer model 52
layout 261
layout design
– electronic 254
layout synthesis 256
LDS paint 212
LDS plastic 59
LDS prototypes 211
LDS systems 271
leadframes 8
lead-free solder processes 45
LED camera module 288
LEDs 77
liquid crystal polymers 44
loss factor 33
loss modulus 33
LPKF-LDS® process 55, 65

M
M22 LED arrays 298
macro-MID 271

macromolecules 25
manufacturing rule checks 259
manufacturing rules 256
masking 5, 73
materials development and selection 27
MCAD 261
measurement of shear force 187
mechanical characteristic values 29
mechanical damping 33
mechanical design 254
mechanical MID functions 247
mechanical service limits 45
mechatronic integrated devices 1
medical technology 10, 284, 286, 295
metallization 96
– galvano-chemical 97
metal particle 92
metals 23, 28
microphone carrier 295
microscopic integrated processing technology (MIPTEC) 71
MID 1
MIDCAD 263
MID functions
– electrical 247
– mechanical 247
MID product model 259
MID prototyping 201, 215
MID-specific development tool 263
MID structuring processes 95
MIPTEC 71
moisture absorption 193
moldable compounds, thermoset 59
molded interconnect device 1
MRC 259
multiband antenna 280
multilayer ceramic 71
MULTI LED 284
multi-material systems 35

N
NCA 145
network 20
NEXTRA® 264
no-flow underfill 163
nonconductive adhesives 145, 147
nonmetals 23

O
ohmic heating 191
OLED 278
one-shot molding 58
optical function 12
optical inspection 135
overspray 94

P
package 11
painting 171
PCK process 53, 85
peel resistance 183
peel test 182
periphery, interfacing to 169
phase, intermetallic 149
photo-chemical ablation 55
photoresist 72
pick & place machines 125, 126, 132
piezoelectric drives 128
piezo print head 78
pin transfer 121
placement 115, 123, 263
plasma, cold 92
Plasmadust® 92
plasma structuring 5
plasma technologies 91
plastic compounds 49
plastic injection molding 265
plastics 25
– thermoplastic 26
plastics characteristic values 27
plastics pyramid 39
platelets 51
plug connectors 12
polyaddition 25
polyamide 43
polybutylene terephthalate 43
polycarbonate 42
polycarbonate HT 42
polycondensation 25
polyetherimide 44
polyethersulfone 44
polymerization 25
polymers, liquid crystal 44
polyphenylene oxide 41
polyphenylene sulfide 43
polypropylene 40
polystyrene, syndiotactic 41
positioning 264
powders 51
prepared section 188

preproduction 272
press-in connection 147, 160, 198
press-in connection technique 159
press-in pin 147
press insert molding 86, 87
pressure sensor 283
primer technology 5, 89
printed circuit board Kollmorgen 53, 85
printed-circuit boards 8
Aerosol-Jet® printing 74
printing techniques 74
printing technologies 5
process chain 113
process cost calculation 233
process surfaces 114
product conceptualization 227
production control 271, 273
production-process conceptualization 229
product optimization 221
product quality 173
protection against environmental influences 170
ProtoPlate LDS® 101
– process 210
prototype 201, 204
pull-off test 183
pull test 187
puncture resistance, electrical 38
puncture test 32
PVD 93

Q

quality assurance 173

R

radiation-induced crosslinking 46, 47
radio frequency identification 77
rapid prototyping 201
rapid tooling 209, 213, 214
reference marks 117
reference process, MID 6
reflow convection soldering 151
reflow infrared soldering 151
reflow soldering 113, 134, 149
reflow vapor-phase soldering 152
relaxation 55
reliability analysis 192
Research Association Molded Interconnect Devices (3D-MID) 20
RFID 77
Rockwell 31
Rockwell α hardness 31
routing 263, 264

S

sample 201
Sankyo Kasei wiring board 53, 85
screw dispenser 120
seat-adjustment switch 296
security caps 292
σ/e diagrams 30
selective laser melting 206, 210
selective laser sintering 206
selective soldering processes 155
semifinished product 209, 212
sensor technology 11
series-production applications 277
service limits
– mechanical 45
– thermal 45
shear pull test 184
shock test 195
Shore hardnesses 32
simulation 175, 265
SKW process 53, 85
smartphones 280
SMD components 141
SMD pick & place machines 125, 126, 132
smoothing 103
SMT 115, 141
soft soldering 149
software tools 261
solar sensor 294
solder bumps 167
soldering processes 153
– lead-free 45
– selective 155
solder joint 149
solder paste 143
solder-stop paint 150
SPICE tools 239
standard thermoplastics 39
stenciling 167
stencil printing 119
STEP 259, 272
stereolithography 205
– process 205
storage modulus 33
strain/elongation diagrams 29
structure, chemical 24

structuring processes 63
stud bump 167
substrate materials 39
surface mount devices 115
surface mount technology 115, 141
surface resistance 192
surface resistivity 37
surface roughness 56
syndiotactic polystyrene 41
SysML, Systems Modeling Language 225

T
tampon printing 91
tape test 185, 186
telecommunications 10, 280
temperature cycling test 195
tensile impact test 32
tensile test 29
testing methods 176, 182
thermal conductivity 49
thermal expansion 35, 36
thermal service limits 45
thermal strain 36
thermoplastic foam molding 86
thermoplastics 26
thermoplastics, engineering 39
thermoset injection molding 60
thermoset moldable compounds 59
thermoset plastics 25
thermo-sonic ball-wedge bonding 164
thermo-sonic bonding (TS) 164
three-dimensional development environment 256
through-hole technology 141
THT 141
transfer decal process 88
two-shot MID 214
two-shot molding 5, 53, 84

U
UHF RFID transponder 287
ultrasonic (US) wedge-wedge bonding 164
underfill 163

V
vacuum casting 208, 212
vapor-phase soldering 134, 154
vibration test 195
Vickers hardness 32
visualization sample 202
V model 219
VOC-free 92
volume resistivity 37

W
wafer bumping 167
wafer level solder sphere transfer process (WLSST) 167
water-jet cleaning 97
weld line 194
wet-chemical cleaning 96
wetting 150
wire bonding 162, 164
workpiece carrier 126, 134
– automated 132, 133, 134
work planning 244

X
X-ray analysis 179
X-ray fluorescence analysis 181